

# Huawei Ascend 960

Da Vinci v4 (chiplet)

OAM

2027

## OVERVIEW

— FP32 TFLOPS	<b>288 GB</b> VRAM	<b>9.6 TB/s</b> Memory Bandwidth	— TDP
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## PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
FP8	2000.0	8	Standard
FP4	4000.0	4	Standard
FP16	1000.0	16	Standard
BF16	1000.0	16	Standard

## MEMORY SPECIFICATIONS

Capacity	288 GB	TDP	—
Type	—	Est. Max Power	—
Bandwidth	9.6 TB/s	FP32 Efficiency	—
Interface Width	—	FP16 Efficiency	—

## POWER & EFFICIENCY

## HARDWARE DETAILS

Vendor: Huawei	Architecture: Da Vinci v4 (chiplet)	Process Node: —
Form Factor: OAM	Launch Year: 2027	

## INTERCONNECT

GPU-to-GPU: Unified Bus 2.0	Bandwidth: 2.2 TB/s
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